

preliminary

Thyristor Module

 $V_{RRM} = 2 \times 1600V$ $I_{TAV} = 700A$ $V_T = 1.16V$

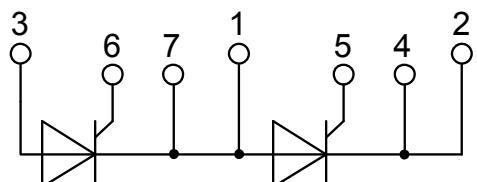
Phase leg

Part number

MCMA700P1600CA



Backside: isolated



Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability
- Direct Copper Bonded Al₂O₃-ceramic

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

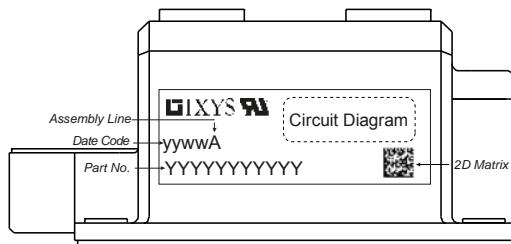
Package: ComPack

- Isolation Voltage: 4800 V~
- Industry standard outline
- RoHS compliant
- Base plate: Copper internally DCB isolated
- Advanced power cycling

Rectifier

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1700	V
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1600	V
I_{RD}	reverse current, drain current	$V_{RD} = 1600 V$	$T_{VJ} = 25^\circ C$		2	mA
		$V_{RD} = 1600 V$	$T_{VJ} = 125^\circ C$		40	mA
V_T	forward voltage drop	$I_T = 700 A$	$T_{VJ} = 25^\circ C$		1.20	V
		$I_T = 1400 A$			1.45	V
		$I_T = 700 A$	$T_{VJ} = 125^\circ C$		1.16	V
		$I_T = 1400 A$			1.46	V
I_{TAV}	average forward current	$T_C = 85^\circ C$ 180° sine	$T_{VJ} = 140^\circ C$		700	A
V_{TO} r_T	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 140^\circ C$		0.82	V
					0.4	mΩ
R_{thJC}	thermal resistance junction to case				0.05	K/W
R_{thCH}	thermal resistance case to heatsink			0.02		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ C$		2300	W
I_{TSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$		19.0	kA
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		20.5	kA
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 140^\circ C$		16.2	kA
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		17.4	kA
I^2t	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$		1.81	MA²s
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		1.75	MA²s
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 140^\circ C$		1.30	MA²s
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		1.27	MA²s
C_J	junction capacitance	$V_R = 400 V$ $f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ C$	876		pF
P_{GM}	max. gate power dissipation	$t_p = 30 \mu s$	$T_C = 140^\circ C$		240	W
		$t_p = 300 \mu s$			120	W
P_{GAV}	average gate power dissipation				40	W
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 140^\circ C; f = 50 \text{ Hz}$	repetitive, $I_T = 2100 A$		100	A/μs
		$t_p = 200 \mu s; di_G/dt = 1 A/\mu s;$				
		$I_G = 1 A; V_D = \frac{2}{3} V_{DRM}$	non-repet., $I_T = 700 A$		500	A/μs
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 140^\circ C$		1000	V/μs
		$R_{GK} = \infty$; method 1 (linear voltage rise)				
V_{GT}	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^\circ C$		2	V
			$T_{VJ} = -40^\circ C$		3	V
I_{GT}	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^\circ C$		300	mA
			$T_{VJ} = -40^\circ C$		400	mA
V_{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 140^\circ C$		0.25	V
I_{GD}	gate non-trigger current				10	mA
I_L	latching current	$t_p = 30 \mu s$	$T_{VJ} = 25^\circ C$		400	mA
		$I_G = 1 A; di_G/dt = 1 A/\mu s$				
I_H	holding current	$V_D = 6 V$ $R_{GK} = \infty$	$T_{VJ} = 25^\circ C$		300	mA
t_{gd}	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25^\circ C$		2	μs
		$I_G = 1 A; di_G/dt = 1 A/\mu s$				
t_q	turn-off time	$V_R = 100 V; I_T = 700 A; V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 140^\circ C$	350		μs
		$di/dt = 10 A/\mu s; dv/dt = 50 V/\mu s; t_p = 200 \mu s$				

Package ComPack			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			1200	A
T_{VJ}	virtual junction temperature		-40		140	°C
T_{op}	operation temperature		-40		125	°C
T_{stg}	storage temperature		-40		125	°C
Weight				500		g
M_D	mounting torque		3		5	Nm
M_T	terminal torque		12		14	Nm
$d_{Spp/App}$	creepage distance on surface / striking distance through air		terminal to terminal	21.0		mm
$d_{Spb/Abp}$			terminal to backside	18.0		mm
V_{ISOL}	isolation voltage	$t = 1$ second $t = 1$ minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA		4800 4000	V V



Part description

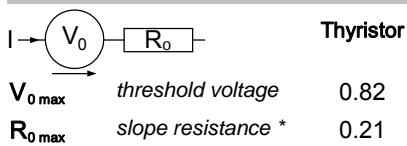
M = Module
 C = Thyristor (SCR)
 M = Thyristor
 A = (up to 1800V)
 700 = Current Rating [A]
 P = Phase leg
 1600 = Reverse Voltage [V]
 CA = ComPack

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MCMA700P1600CA	MCMA700P1600CA	Box	2	513835

Equivalent Circuits for Simulation

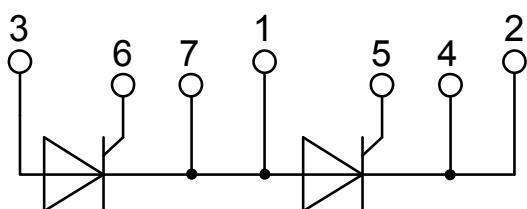
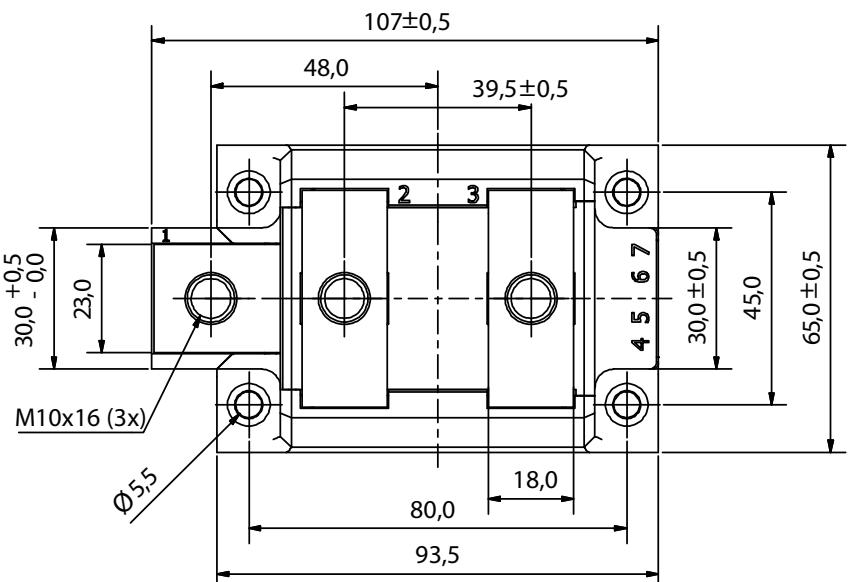
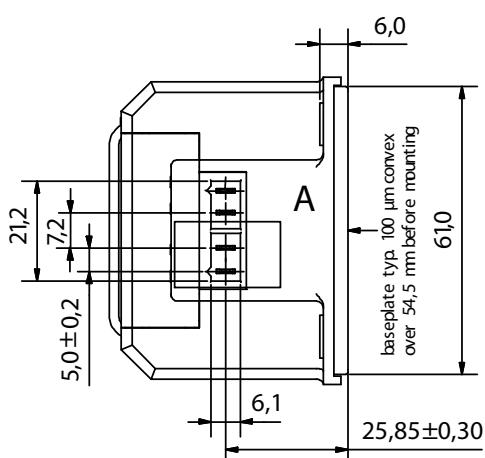
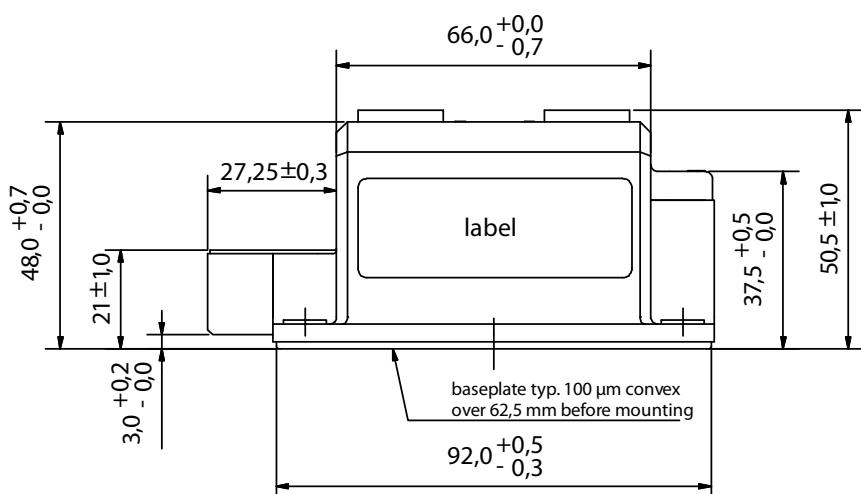
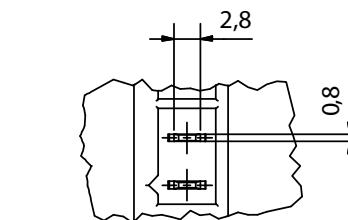
* on die level

$T_{VJ} = 140$ °C



Outlines ComPack

A (2 : 1)



Thyristor

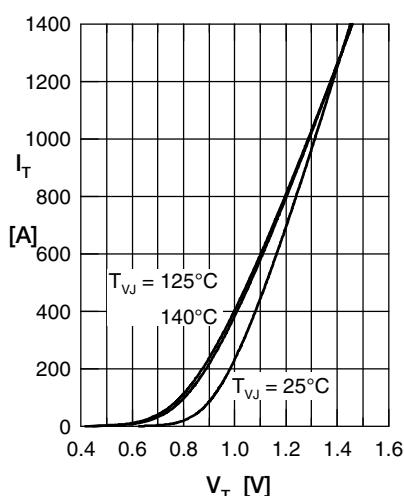


Fig. 1 Forward characteristics

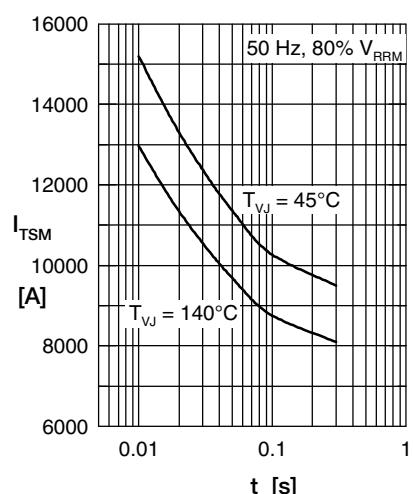
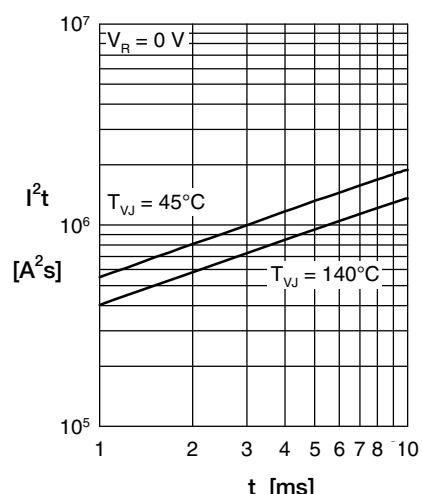
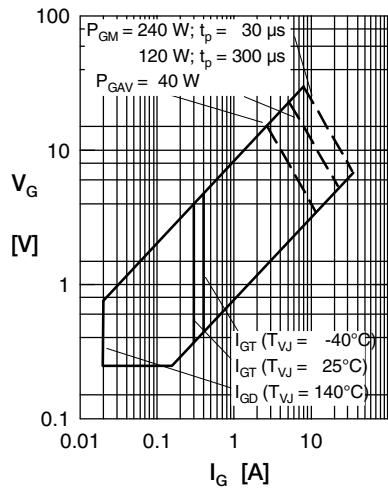
Fig. 2 Surge overload current
 I_{TSM} : crest value, t : durationFig. 3 I^2t versus time (1-10 s)

Fig. 4 Gate voltage & gate current

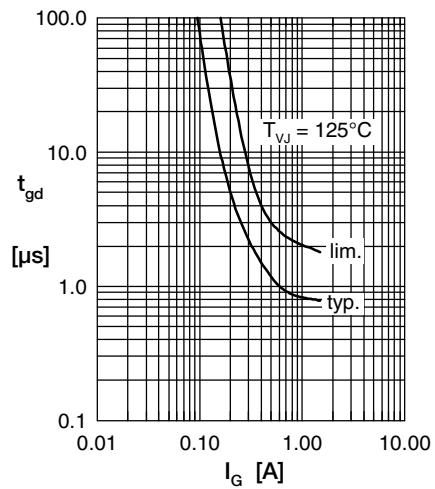
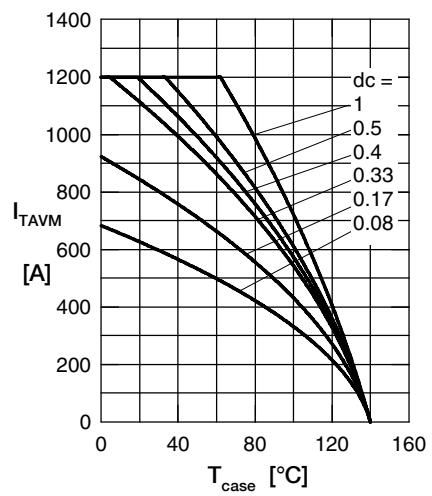
Fig. 5 Gate controlled delay time t_{gd} 

Fig. 6 Max. forward current at case temperature

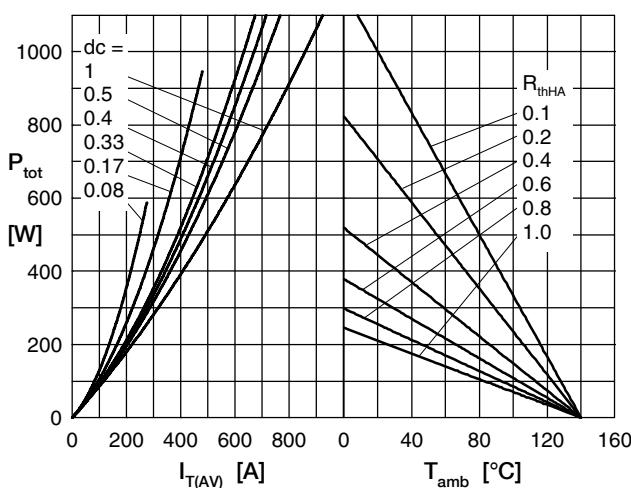
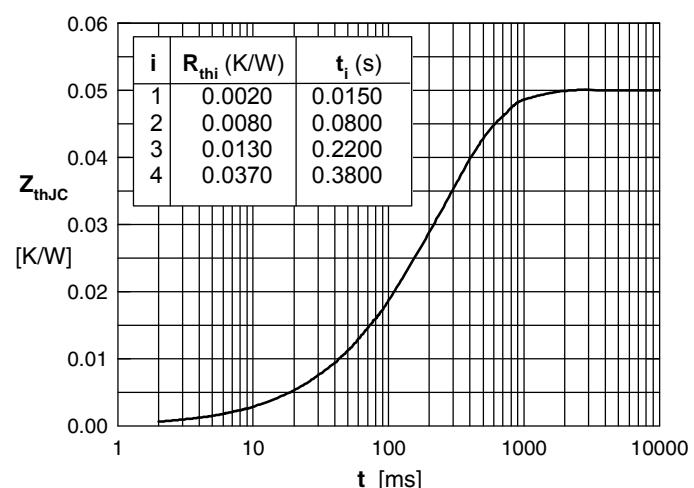
Fig. 7a Power dissipation versus direct output current
Fig. 7b and ambient temperature

Fig. 8 Transient thermal impedance junction to case